

# PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
Name		Execution Date
HUN KIM		06/24/2008
BYUNG SOO EUN		06/24/2008
RECEIVING PARTY DATA		
Name:	HYNIX SEMICONDUCTOR INC.	
Street Address:	San 136-1, Ami-ri, Bubal-eub, Icheon-si	
City:	Kyoungki-do	
State/Country:	KOREA, REPUBLIC OF	
PROPERTY NUMBERS Total: 1		
Property Type	Number	
Application Number:	12169708	
CORRESPONDENCE DATA		
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ATTORNEY DOCKET NUMBER:	CU-6821 WWP/NK	
NAME OF SUBMITTER:	Woochoon W. Park	
Total Attachments: 2 source=cu6821assign#page1.tif source=cu6821assign#page2.tif		

CH \$40.00 12169708

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PATENT  
REEL: 021210 FRAME: 0266

**UNITED STATES OF AMERICA**  
**ASSIGNMENT**

In consideration of the payment of ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for the other good and valuable consideration,

**ASSIGNOR:**

Name : Hun KIM

Address : 101-607, Worim Lumiat, 45, Gil-dong, Gangdong-gu, Seoul, Korea

Name: Byung Soo EUN

Address: #201, 412-374, Sinrimbon-dong, Gwanak-gu, Seoul, Korea

(INVENTOR NAME AND ADDRESS)

hereby sells, assigns and transfers to

**ASSIGNEE:**

Name : Hynix Semiconductor Inc.

Address : San 136-1, Ami-ri, Bubal-eub, Icheon-si, Kyoungki-do, Korea

(ASSIGNEE NAME AND ADDRESS)

and the successors, assigns and legal representatives of the ASSIGNEE the entire right, title and interest for the United States and its territorial possessions in and to, any and all improvements which are disclosed in the invention entitled:  
SEMICONDUCTOR DEVIC FOR PREVENTING THE LEANING OF STORAGE NODES AND METHOD  
FOR MANUFACTURING THE SAME

(TITLE)

and which is found in *(check one applicable item below)*

☒ U.S. patent application executed on even date herewith

☐ U.S. Application Serial No. \_\_\_\_\_ filed on \_\_\_\_\_

and, in and to all Letters Patent to be obtained for said invention by the above application or any continuation, division, renewal, substitute, reissue or re-examination thereof.

ASSIGNOR hereby convenants that no assignment, sale agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale;

ASSIGNOR further convenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters

Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference or litigation related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the purposes thereof.

IN WITNESS WHEREOF, I/we have set our hand and seal

June 24, 2008

Date

Hun Kim

INVENTOR: Hun KIM

June 24, 2008

Date

Eun Byung Soo

INVENTOR: Byung Soo EUN

0699P/1

한국특허청  
2008/06/24

PATENT

RECORDED: 07/09/2008

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